

P-Ch MOSFET

General Description

The WSD4018DN22 is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSD4018DN22 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

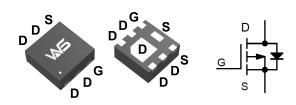
Product Summery

BVDSS	RDSON	ID
-40V	26mΩ	-18A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN2X2-6L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage -40		V	
V _{GS}	Gate-Source Voltage ±20		V	
I _D @T₀=25℃	Continuous Drain Current, V _{GS} @ -10V ¹ -18			
I _D @T₀=70°C	Continuous Drain Current, V _{GS} @ -10V ¹ -14.6		A	
I _{DM}	300µS Pulsed Drain Current,V _{GS} =-4.5V ²	54	A	
P₀@T₀=25℃	Total Power Dissipation ³	19	W	
T _{STG}	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		36	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		6.5	℃ /W



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Electrical Characteristics (T _J =25	℃, unless otherwise noted)
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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-40			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=-1mA		-0.01		V/℃
	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-8.0A		26	34	mΩ
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-6.0A		31	42	
V _{GS(th)}	Gate Threshold Voltage		-1.0	-1.5	-3.0	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS} = V_{DS}$, $I_D = -2500A$		3.13		mV/℃
	Drain-Source Leakage Current	V_{DS} =-40V , V_{GS} =0V , T _J =25 $^\circ$ C			-1	
I _{DSS}		V _{DS} =-40V , V _{GS} =0V , T _J =55℃			-5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA
Qg	Total Gate Charge (-4.5V)			27		
Q _{gs}	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-10V , I _D =-1.5A		2.5		nC
Q _{gd}	Gate-Drain Charge			6.7]
T _{d(on)}	Turn-On Delay Time			9.8		
Tr	Rise Time	V _{DD} =-20V , V _{GS} =-10V ,		11		
T _{d(off)}	Turn-Off Delay Time	R _G =3Ω , RL=10Ω		54		ns
T _f	Fall Time			7.1]
C _{iss}	Input Capacitance			1560		
C _{oss}	Output Capacitance	V _{DS} =-20V , V _{GS} =0V , f=1MHz		116		pF
C _{rss}	Reverse Transfer Capacitance			97		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}	$V_G = V_D = 0V$, Force Current			-18	А
V _{SD}	Diode Forward Voltage ²	$V_{GS}\text{=}0V$, $I_{S}\text{=}\text{-}1A$, $T_{J}\text{=}25^{\circ}\!\!\mathbb{C}$			-1.2	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t \leq 10sec.

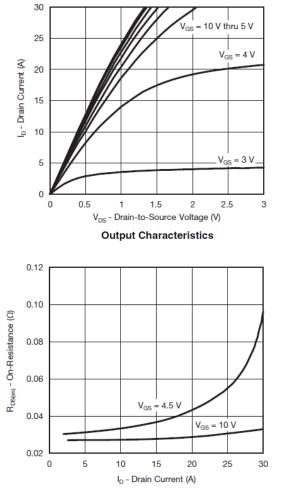
2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ junction temperature

4. The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

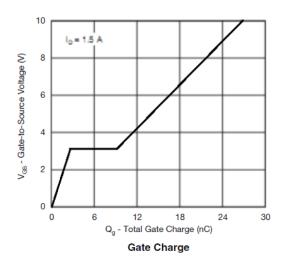


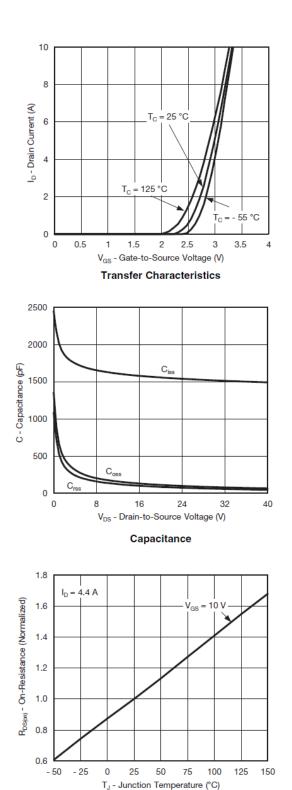
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Typical Performance Characteristics ((TJ = 25 °C, unless otherwise noted))

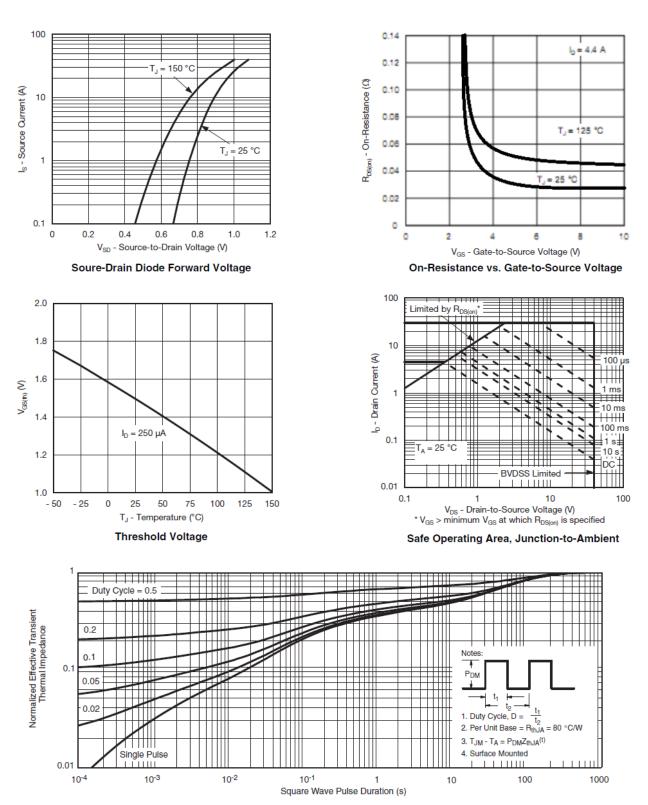
On-Resistance vs. Drain Current and Gate Voltage







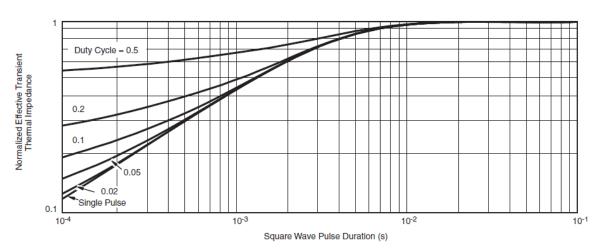
P-Ch MOSFET



Normalized Thermal Transient Impedance, Junction-to-Ambient



P-Ch MOSFET



Normalized Thermal Transient Impedance, Junction-to-Case



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